

## 30V P-Channel Enhancement Mode Power MOSFET

### Description

WMS12P03T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

### Features

- $V_{DS} = -30V$ ,  $I_D = -11.5A$   
 $R_{DS(on)} < 15m\Omega$  @  $V_{GS} = -10V$   
 $R_{DS(on)} < 25m\Omega$  @  $V_{GS} = -4.5V$
- High Power and Current Handling Capability
- Low Gate Charge

### Applications

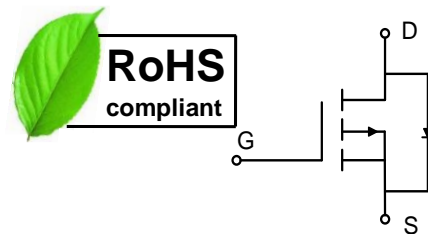
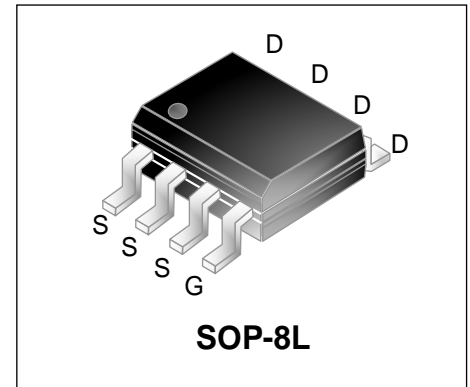
- Power Management Switches
- Battery Protection Applications

### Absolute Maximum Ratings

Parameter		Symbol	Value	Unit
Drain-Source voltage		$V_{DS}$	-30	V
Gate-Source voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current@-10V <sup>1</sup>	$T_A = 25^\circ C$	$I_D$	-11.5	A
	$T_A = 70^\circ C$		-9	
Pulsed Drain Current <sup>2</sup>		$I_{DM}$	-46	A
Single Pulse Avalanche Energy <sup>3</sup>		<b>EAS</b>	125	mJ
Avalanche Current		$I_{AS}$	-50	A
Total Power Dissipation <sup>4</sup>	$T_A = 25^\circ C$	<b>P<sub>D</sub></b>	1.5	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to +150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	<b>R<sub>θJA</sub></b>	75	$^\circ C/W$
Thermal Resistance from Junction-to-Case <sup>1</sup>	<b>R<sub>θJC</sub></b>	24	$^\circ C/W$



**Electrical Characteristics**  $T_c = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30	-	-	V
Gate-body Leakage current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$T_J=25^\circ\text{C}$	$I_{DSS}$ $V_{DS} = -24V, V_{GS} = 0V$	-	-	-1	$\mu A$
	$T_J=55^\circ\text{C}$		-	-	-5	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.0	-	-2.5	V
Drain-Source On-Resistance <sup>2</sup>	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -10A$	-	11	15	m $\Omega$
		$V_{GS} = -4.5V, I_D = -10A$	-	16	25	
Forward Transconductance	$g_{fs}$	$V_{DS} = -5V, I_D = -10A$	-	24	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -15V, V_{GS} = 0V, f = 1\text{MHz}$	-	2335	-	pF
Output Capacitance	$C_{oss}$		-	280	-	
Reverse Transfer Capacitance	$C_{rss}$		-	219	-	
<b>Switching Characteristics</b>						
Gate Resistance	$R_g$	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	-	9	-	$\Omega$
Total Gate Charge	$Q_g$	$V_{GS} = -4.5V, V_{DS} = -15V$ $I_D = -10A$	-	20	-	nC
Gate-Source Charge	$Q_{gs}$		-	5.1	-	
Gate-Drain Charge	$Q_{gd}$		-	7.3	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = -10V, V_{DD} = -15V$ $R_G = 3.3\Omega, I_D = -1A$	-	33.8	-	nS
Rise Time	$t_r$		-	35.8	-	
Turn-Off Delay Time	$t_{d(off)}$		-	72.8	-	
Fall Time	$t_f$		-	10.6	-	
<b>Drain-source body diode Characteristics</b>						
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	$I_S = -1A, V_{GS} = 0V$	-	-	-1	V
Continuous Source Current <sup>1,5</sup>	$I_S$	$V_G=V_D=0V, \text{Force Current}$	-	-	-11.5	A
Pulsed Source Current <sup>2,5</sup>	$I_{SM}$		-	-	-46	

## Notes:

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- The EAS data shows Max. rating . The test condition is  $V_{DD} = -25V, V_{GS} = -10V, L = 0.1\text{mH}, I_{AS} = -50A$
- The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

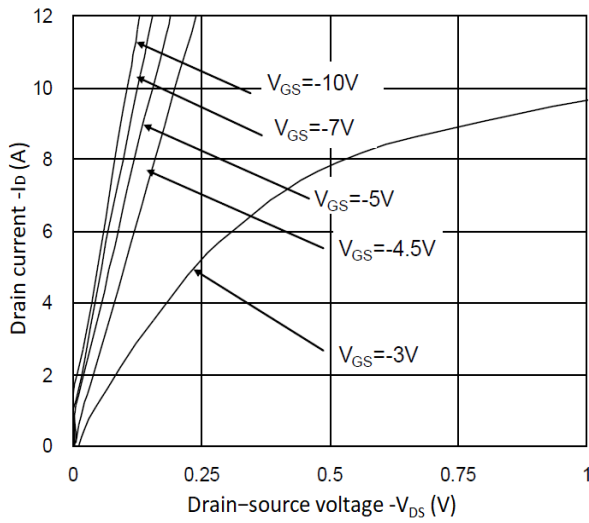


Figure 1. Typical Output Characteristics

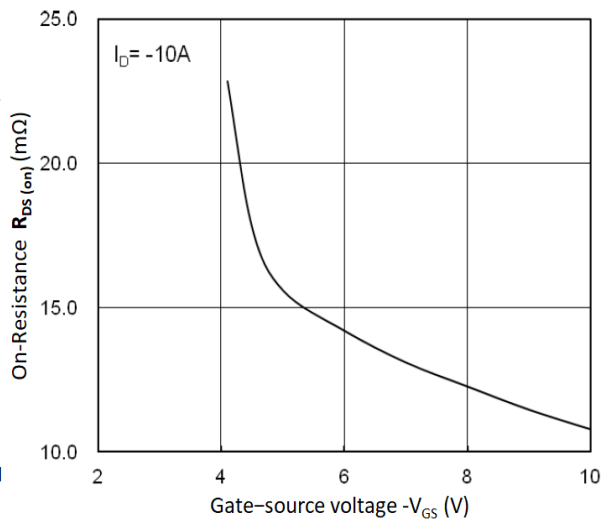


Figure 2.  $R_{DS(on)}$  vs.  $V_{GS}$

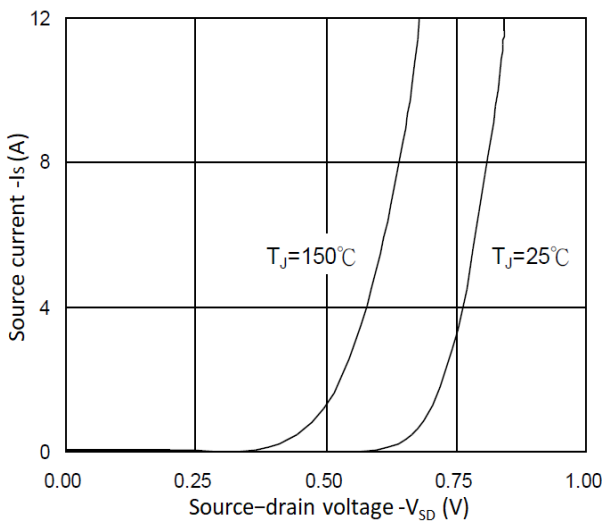


Figure 3. Forward Characteristics of Reverse

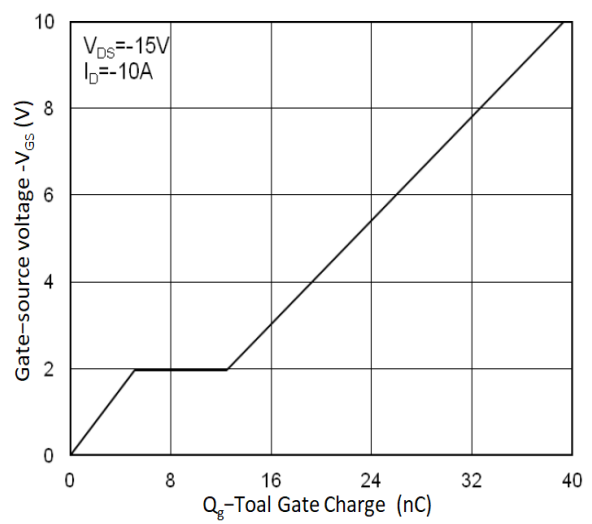


Figure 4. Gate Charge Characteristics

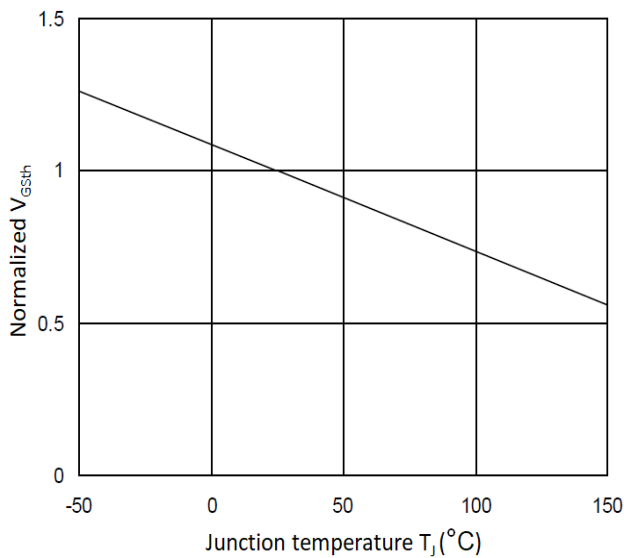


Figure 5. Normalized  $V_{GS(th)}$  vs.  $T_J$

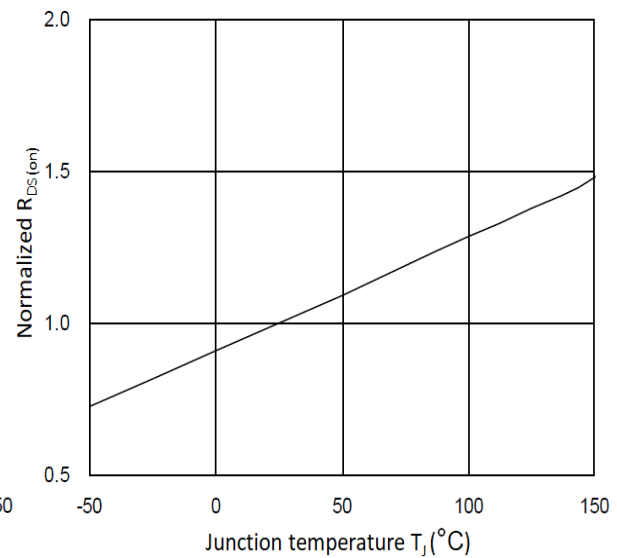


Figure 6. Normalized  $R_{DS(on)}$  vs.  $T_J$

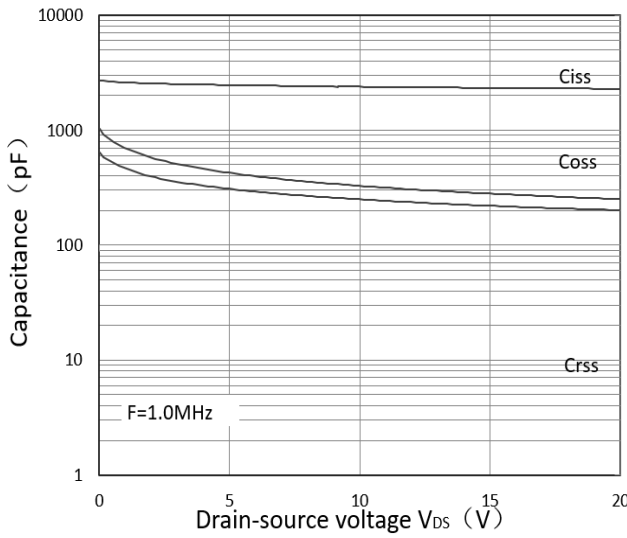


Figure 7. Capacitance Characteristics

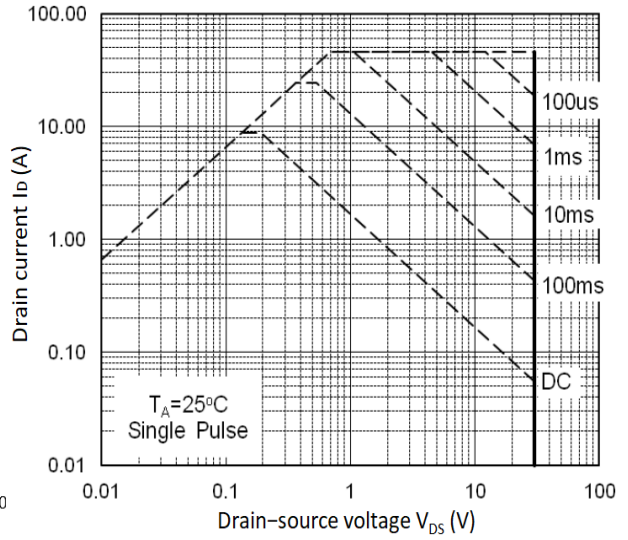


Figure 8. Safe Operating Area

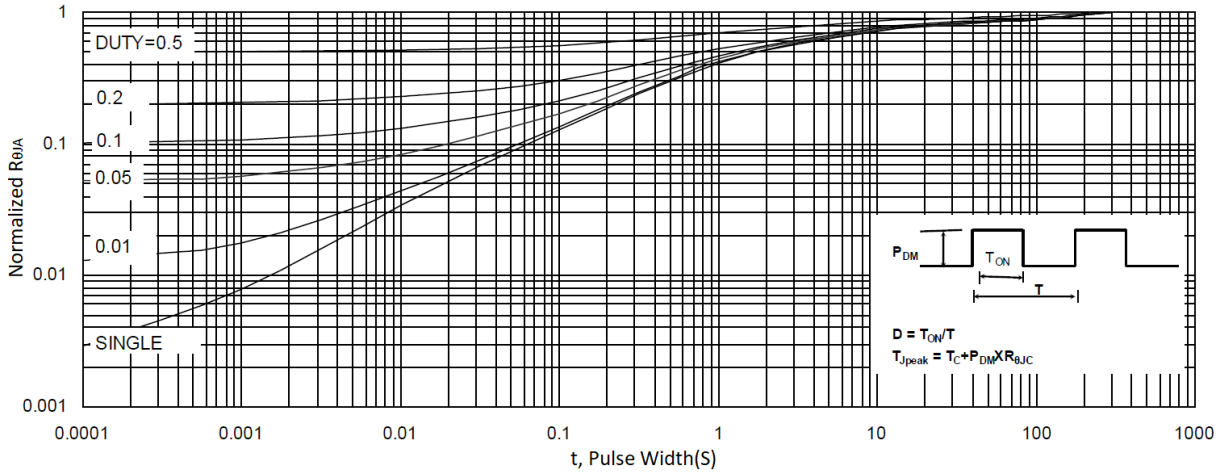


Figure 9. Normalized Maximum Transient Thermal Impedance

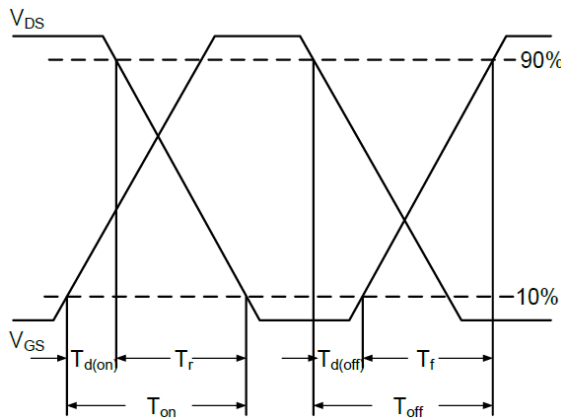


Figure 10. Switching Time Waveform

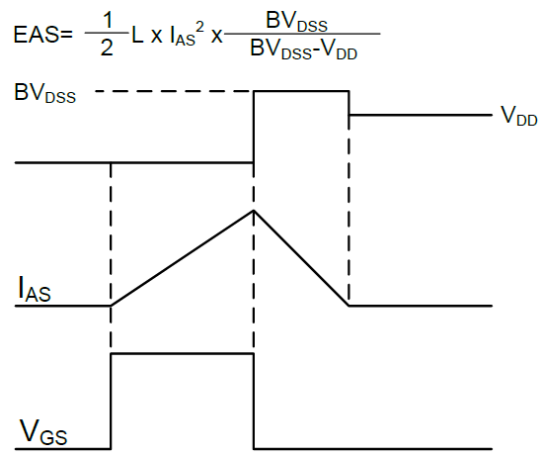
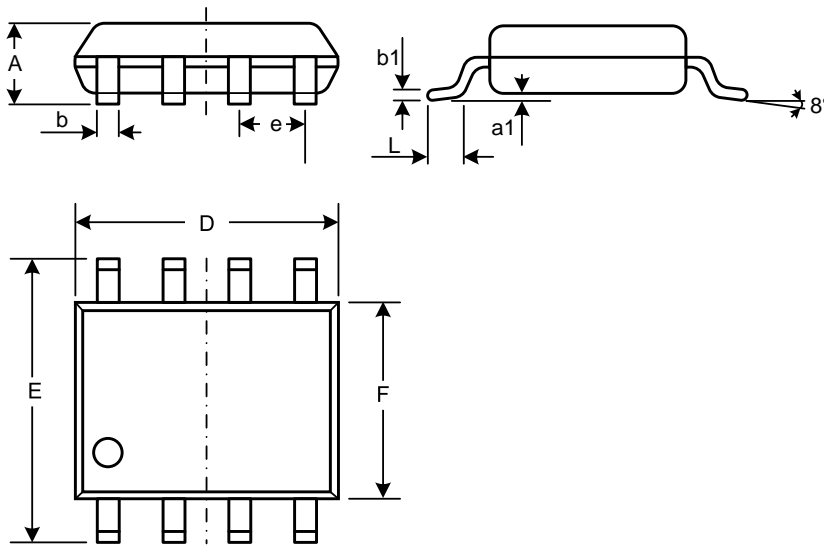


Figure 11. Unclamped Inductive Switching Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

Mechanical Dimensions for SOP-8L



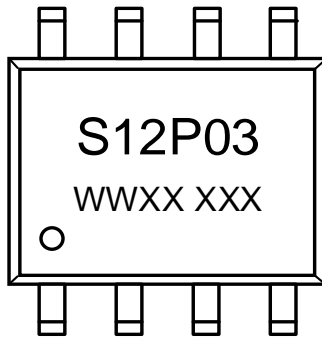
COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	1.23	1.75
a1	0.05	0.25
b	0.31	0.51
b1	0.16	0.25
D	4.70	5.15
E	5.75	6.25
e	1.07	1.47
F	3.70	4.10
L	0.4	1.27

## Ordering Information

Part	Package	Marking	Packing method
WMS12P03T1	SOP-8L	S12P03	Tape and Reel

## Marking Information



S12P03 = Device code

WWXX XXX= Date code


## Contact Information

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